

C0402C101K5HACTU

Aliases (C0402C101K5HAC7867) SMD Comm X8R HT150C, Ceramic, 100 pF, 10%, 50 VDC, X8R, SMD, MLCC, High Temperature, Ultra-Stable, 0402, 0.3 mm



General Information			
Series	SMD Comm X8R HT150C		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Typical Component Weight	1.21 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
S	0.3mm MIN
В	0.3mm +/-0.1mm

Packaging Specifications	
В	0.3mm +/-0.1mm
S	0.3mm MIN
1	0.5mm +/-0.05mm

Specifications			
Capacitance	100 pF		
Measurement Condition	1 MHz 1.0Vrms		
Tolerance	10%		
Voltage DC	50 VDC		
Dielectric Withstanding Voltage	125 VDC		
Temperature Range	-55/+150°C		
Temp. Coefficient	X8R		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1MegaHz 1.0Vrms		
Dissipation Factor	2.5% 1 MHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours		
Insulation Resistance	100 GOhms		

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		Temp. Coefficient		X8R
Packaging Specifications		Capacitance Change with	ange with	15%, 1MegaHz 1.0Vrms
Packaging	T&R, 180mm, Paper Tape	Reference to +25°C and 0 VDC Applied (TCC)	·	
Packaging Quantity 10	10000	Dissipation Fact	tor	2.5% 1 MHz 1.0Vrms
		Aging Rate		0% Loss/Decade Hour: Referee Time is 1000 Hours
		Insulation Resis	tance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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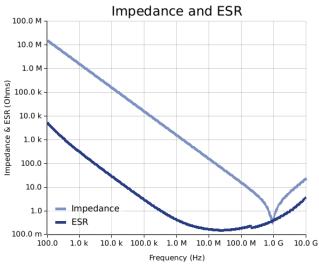


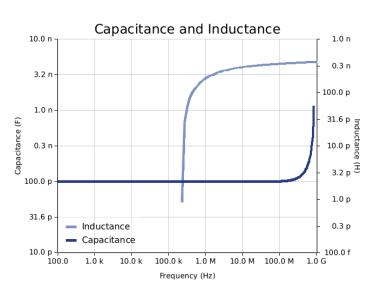
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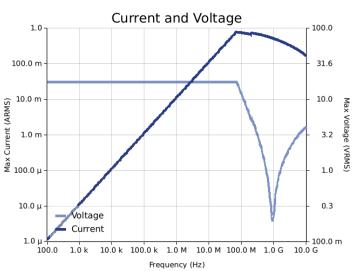
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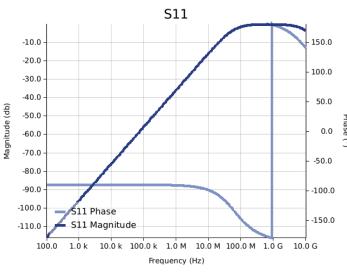
Simulations

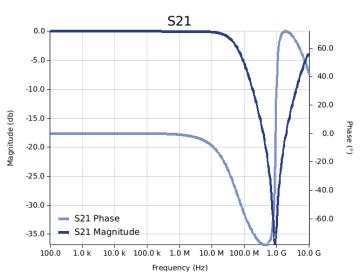
For the complete simulation environment please visit Y-SIM.











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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR in the "Temperature Rise vs. Ripple Current" plots is the ESR at ambient temperature. The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated. The effects shown herein are based on measured data from a multiple part sample of the parts in question. Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

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